

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of : Customer Number: 89518  
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 LIN, Mou-Shiung, et al. : Confirmation Number: 8665  
 :  
 Application No.: 10/755,042 : Group Art Unit: 2815  
 :  
 Filed: January 09, 2004 : Examiner: JACKSON JR., Jerome  
 :  
 For: INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON SUBSTRATE AND METHOD OF  
 MANUFACTURING THE SAME

**TRANSMITTAL**

Mail Stop RCE  
 Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

**CERTIFICATE OF ELECTRONIC TRANSMISSION**

I hereby certify that this correspondence is being electronically-transmitted to the  
 United States Patent and Trademark Office on June 27, 2011

/s/lynne j. craig/  
 Lynne J. Craig

Dear Sir:

Transmitted herewith is Request for Continued Examination, an Amendment/Response and two Information Disclosure Statements in the above-identified application.

The fee has been calculated as shown below:

	NO. OF CLAIMS	HIGHEST PREVIOUSLY PAID FOR	EXTRA CLAIMS	RATE	FEE
Total Claims	44	47	0	\$52.00 =	\$0.00
Independent Claims	3	3	0	\$220.00 =	\$0.00
Fee for extension of time					\$0.00
Request for Continued Examination					\$810.00
Total of Above Calculations					\$810.00

☒ Please charge my Deposit Account No. 502624 in the amount of \$810.00.

☒ The Commissioner is hereby authorized to charge payment of any fees associated with this communication or credit any overpayment, to Deposit Account No. 502624, including any filing fees under 37 CFR 1.16 for presentation of extra claims and any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

McDERMOTT WILL & EMERY LLP

/Dennis A. Duchene/  
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**Date: June 27, 2011**

**Please recognize our Customer No. 89518 as our  
 correspondence address.**